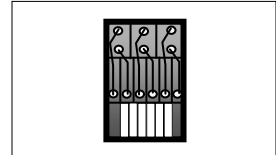
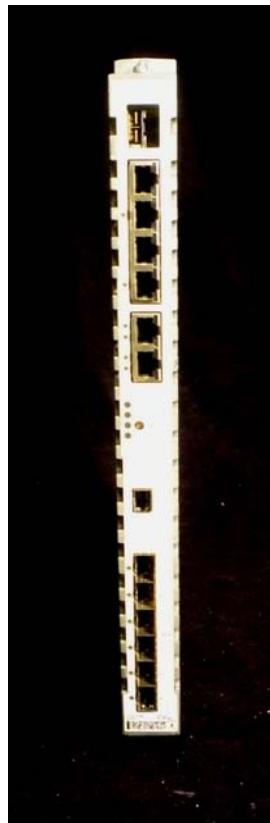


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**Ericsson GSM Baseband Unit
KDU 137 569/1 R2B
Model DUG20 01**

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